

EF-51 Series 0.5mm Pitch, Front Flip Lock Type (SMT)



Features

1. Our original front flip lock structure ensures multi pins products of high level contact reliability.
 - The structure which relieves the load from the cover when the FPC is locked will prevent detachment or breakage of the cover.
 - There are no restrictions to the direction in which the FPC can be laid.
2. By turning the cover, an FPC/FFC can be connected easily with only a small force.
3. Low profile of 2.5mm height when mounted.
4. A small area with a 4.9mm depth will contribute to a reduced PCB mounting area.
5. Lower contact design.
6. With a structure to prevent FPC failing off.
7. Using the ZIF structure.
8. Supplied in the embossed taping with automatic mounter.

Specification

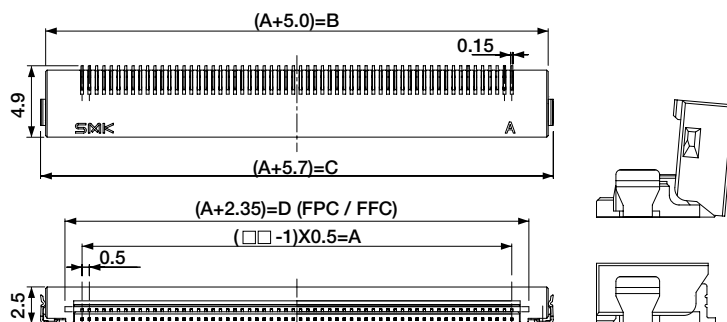
1. Rating: 0.5A, 50V AC/DC
2. Contact Resistance: 30mΩ max., initially
3. Insulation Resistance: 100MΩ min. at 100V DC
4. Withstanding Voltage: 100V AC (for one minute)
5. Operating Temperature Range: -40°C to +85°C

Material and Plating

- Housing: Thermoplastic Resin, Natural Color, 94V-0
- Cover: Thermoplastic Resin, Black, 94V-0
- Contact: Cu Alloy, Au Plating
- Hold-down: Cu Alloy, Sn Plating

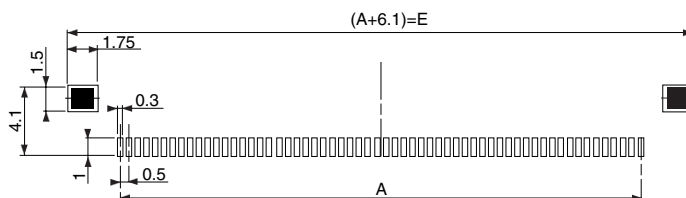
● CFP89 ☐ ☐ -1351F

↑ No. of Pins

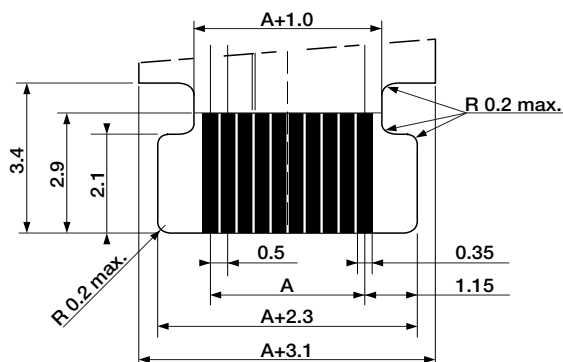


<input type="checkbox"/> <input type="checkbox"/> No. of Pins	A	B	C	D	E
20	9.5	14.5	15.2	11.85	15.6
40	19.5	24.5	25.2	21.85	25.3
45	22.0	27.0	27.7	24.35	27.8
50	24.5	29.5	30.2	26.85	30.3
80	39.5	44.5	45.2	41.85	45.3

■ P.C. Board Dimension



■ Applicable FPC Dimension (t=0.3±0.05)



• Please contact us for the 45 and 80 pins.

• FPC plating to recommend : Au plating